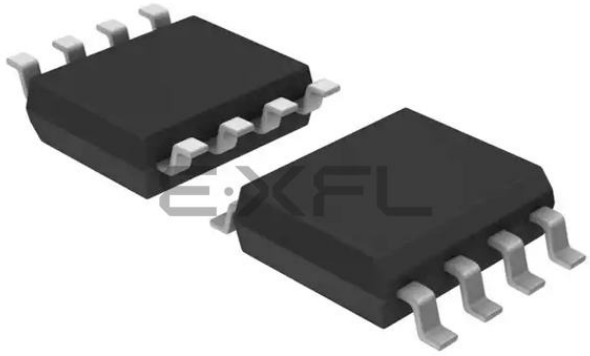

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	eZ8
Core Size	8-Bit
Speed	20MHz
Connectivity	IrDA, UART/USART
Peripherals	Brown-out Detect/Reset, LED, LVD, POR, PWM, Temp Sensor, WDT
Number of I/O	6
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	8-SOIC (0.154", 3.90mm Width)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8f082asb020sg

Revision History

Each instance in this document's revision history reflects a change from its previous edition. For more details, refer to the corresponding page(s) or appropriate links furnished in the table below.

Date	Revision Level	Chapter/Section	Description	Page No.
Dec 2012	27	Port Alternate Function Mapping (Non 8-Pin Parts), Port Alternate Function Mapping (8-Pin Parts)	Added missing Port D data to Table 15; corrected active Low status (set overlines) for PA0 ($\overline{T0OUT}$), PA2 ($\overline{RESET}$) and PA5 ($\overline{T1OUT}$) in Table 16.	40, 43
Sep 2011	26	LED Drive Enable Register	Clarified statement surrounding the Alternate Function Register as it relates to the LED function; revised Flash Sector Protect Register description; revised Packaging chapter.	53, 157, 245
Sep 2008	25	Overview, Address Space, Register Map, General-Purpose Input/Output, Available Packages, Ordering Information	Added references to F042A Series back in Table 1, Table 5, Table 7 and Table 14.	2, 8, 16, 18, 36, 246
May 2008	24	Overview, Address Space, Register Map, General-Purpose Input/Output, Available Packages, Ordering Information	Changed title to Z8 Encore! XP F082A Series and removed references to F042A Series in Table 1, Table 5, Table 7 and Table 14.	2, 8, 16, 18, 36, 246
Dec 2007	23	Pin Description, General-Purpose Input/Output, Watchdog Timer	Updated Figure 3, Table 15, Tables 60 through 62.	9, 40, 97
Jul 2007	22	Electrical Characteristics	Updated Tables 16 and 132; power consumption data.	43, 229
Jun 2007	21	n/a	Revision number update.	All

Table 2. Signal Descriptions (Continued)

Signal Mnemonic	I/O	Description
Reset		
$\overline{\text{RESET}}$	I/O	RESET. Generates a Reset when asserted (driven Low). Also serves as a reset indicator; the Z8 Encore! XP forces this pin low when in reset. This pin is open-drain and features an enabled internal pull-up resistor.
Power Supply		
V_{DD}	I	Digital Power Supply.
AV_{DD}	I	Analog Power Supply.
V_{SS}	I	Digital Ground.
AV_{SS}	I	Analog Ground.

Notes:
1. PB6 and PB7 are only available in 28-pin packages without ADC. In 28-pin packages with ADC, they are replaced by AV_{DD} and AV_{SS}.
2. The AV_{DD} and AV_{SS} signals are available only in 28-pin packages with ADC. They are replaced by PB6 and PB7 on 28-pin packages without ADC.

Pin Characteristics

Table 3 describes the characteristics for each pin available on the Z8 Encore! XP F082A Series 20- and 28-pin devices. Data in Table 3 is sorted alphabetically by the pin symbol mnemonic.

Table 4 on page 14 provides detailed information about the characteristics for each pin available on the Z8 Encore! XP F082A Series 8-pin devices.

Note: All six I/O pins on the 8-pin packages are 5 V-tolerant (unless the pull-up devices are enabled). The column in Table 3 below describes 5 V-tolerance for the 20- and 28-pin packages only.

Table 7. Register File Address Map (Continued)

Address (Hex)	Register Description	Mnemonic	Reset (Hex)	Page
FD9	Port C Control	PCCTL	00	46
FDA	Port C Input Data	PCIN	XX	46
FDB	Port C Output Data	PCOUT	00	46
GPIO Port D				
FDC	Port D Address	PDADDR	00	44
FDD	Port D Control	PDCTL	00	46
FDE	Reserved	—	XX	
FDF	Port D Output Data	PDOUT	00	46
FE0–FEF	Reserved	—	XX	
Watchdog Timer (WDT)				
FF0	Reset Status (Read-only)	RSTSTAT	X0	29
	Watchdog Timer Control (Write-only)	WDTCTL	N/A	96
FF1	Watchdog Timer Reload Upper Byte	WDTU	00	97
FF2	Watchdog Timer Reload High Byte	WDTH	04	97
FF3	Watchdog Timer Reload Low Byte	WDTL	00	98
FF4–FF5	Reserved	—	XX	
Trim Bit Control				
FF6	Trim Bit Address	TRMADR	00	161
FF7	Trim Bit Data	TRMDR	00	162
Flash Memory Controller				
FF8	Flash Control	FCTL	00	155
FF8	Flash Status	FSTAT	00	155
FF9	Flash Page Select	FPS	00	156
	Flash Sector Protect	FPROT	00	157
FFA	Flash Programming Frequency High Byte	FFREQH	00	158
FFB	Flash Programming Frequency Low Byte	FFREQL	00	158
eZ8 CPU				
FFC	Flags	—	XX	See footnote 2.
FFD	Register Pointer	RP	XX	
FFE	Stack Pointer High Byte	SPH	XX	
FFF	Stack Pointer Low Byte	SPL	XX	

Notes:
1. XX = Undefined.
2. Refer to the eZ8 CPU Core User Manual (UM0128).

Shared Debug Pin

On the 8-pin version of this device only, the Debug pin shares function with the PA0 GPIO pin. This pin performs as a general purpose input pin on power-up, but the debug logic monitors this pin during the reset sequence to determine if the unlock sequence occurs. If the unlock sequence is present, the debug function is unlocked and the pin no longer functions as a GPIO pin. If it is not present, the debug feature is disabled until/unless another reset event occurs. For more details, see the On-Chip Debugger chapter on page 180.

Crystal Oscillator Override

For systems using a crystal oscillator, PA0 and PA1 are used to connect the crystal. When the crystal oscillator is enabled, the GPIO settings are overridden and PA0 and PA1 are disabled. See the Oscillator Control Register Definitions section on page 196 for details.

5V Tolerance

All six I/O pins on the 8-pin devices are 5V-tolerant, unless the programmable pull-ups are enabled. If the pull-ups are enabled and inputs higher than V_{DD} are applied to these parts, excessive current flows through those pull-up devices and can damage the chip.

Note: In the 20- and 28-pin versions of this device, any pin which shares functionality with an ADC, crystal or comparator port is not 5 V-tolerant, including PA[1:0], PB[5:0] and PC[2:0]. All other signal pins are 5 V-tolerant and can safely handle inputs higher than V_{DD} except when the programmable pull-ups are enabled.

External Clock Setup

For systems using an external TTL drive, PB3 is the clock source for 20- and 28-pin devices. In this case, configure PB3 for alternate function CLKIN. Write the Oscillator Control (OSCCTL) Register such that the external oscillator is selected as the system clock. See the Oscillator Control Register Definitions section on page 196 for details. For 8-pin devices, use PA1 instead of PB3.

GPIO Interrupts

Many of the GPIO port pins can be used as interrupt sources. Some port pins can be configured to generate an interrupt request on either the rising edge or falling edge of the pin input signal. Other port pin interrupt sources generate an interrupt when any edge occurs (both rising and falling). See the GPIO Mode Interrupt Controller chapter on page 55 for more information about interrupts using the GPIO pins.

GPIO Control Register Definitions

Four registers for each port provide access to GPIO control, input data and output data. Table 17 lists these port registers. Use the Port A–D Address and Control registers together to provide access to subregisters for port configuration and control.

Table 17. GPIO Port Registers and Subregisters

Port Register Mnemonic	Port Register Name
P*x*ADDR	Port A–D Address Register; selects subregisters.
P*x*CTL	Port A–D Control Register; provides access to subregisters.
P*x*IN	Port A–D Input Data Register.
P*x*OUT	Port A–D Output Data Register.
Port Subregister Mnemonic	**Port Register Name**
P*x*DD	Data Direction.
P*x*AF	Alternate Function.
P*x*OC	Output Control (Open-Drain).
P*x*HDE	High Drive Enable.
P*x*SMRE	Stop Mode Recovery Source Enable.
P*x*PUE	Pull-up Enable.
PxAFS1	Alternate Function Set 1.
PxAFS2	Alternate Function Set 2.

- Set or clear the CTSE bit to enable or disable control from the remote receiver using the $\overline{\text{CTS}}$ pin

6. Check the TDRE bit in the UART Status 0 Register to determine if the Transmit Data Register is empty (indicated by a 1). If empty, continue to Step 7. If the Transmit Data Register is full (indicated by a 0), continue to monitor the TDRE bit until the Transmit Data Register becomes available to receive new data.
7. Write the UART Control 1 Register to select the outgoing address bit.
8. Set the Multiprocessor Bit Transmitter (MPBT) if sending an address byte, clear it if sending a data byte.
9. Write the data byte to the UART Transmit Data Register. The transmitter automatically transfers the data to the Transmit Shift Register and transmits the data.
10. Make any changes to the Multiprocessor Bit Transmitter (MPBT) value, if appropriate and MULTIPROCESSOR Mode is enabled.
11. To transmit additional bytes, return to Step 5.

Transmitting Data using the Interrupt-Driven Method

The UART Transmitter interrupt indicates the availability of the Transmit Data Register to accept new data for transmission. Observe the following steps to configure the UART for interrupt-driven data transmission:

1. Write to the UART Baud Rate High and Low Byte registers to set the appropriate baud rate.
2. Enable the UART pin functions by configuring the associated GPIO port pins for alternate function operation.
3. Execute a DI instruction to disable interrupts.
4. Write to the Interrupt control registers to enable the UART Transmitter interrupt and set the acceptable priority.
5. Write to the UART Control 1 Register to enable MULTIPROCESSOR (9-bit) Mode functions, if MULTIPROCESSOR Mode is appropriate.
6. Set the MULTIPROCESSOR Mode Select (MPEN) to Enable MULTIPROCESSOR Mode.
7. Write to the UART Control 0 Register to:
   - Set the transmit enable bit (TEN) to enable the UART for data transmission
   - Enable parity, if appropriate and if MULTIPROCESSOR Mode is not enabled and select either even or odd parity

The window remains open until the count again reaches 8 (that is, 24 baud clock periods since the previous pulse was detected), giving the Endec a sampling window of minus four baud rate clocks to plus eight baud rate clocks around the expected time of an incoming pulse. If an incoming pulse is detected inside this window this process is repeated. If the incoming data is a logical 1 (no pulse), the Endec returns to the initial state and waits for the next falling edge. As each falling edge is detected, the Endec clock counter is reset, resynchronizing the Endec to the incoming signal, allowing the Endec to tolerate jitter and baud rate errors in the incoming datastream. Resynchronizing the Endec does not alter the operation of the UART, which ultimately receives the data. The UART is only synchronized to the incoming data stream when a Start bit is received.

Infrared Encoder/Decoder Control Register Definitions

All infrared endec configuration and status information is set by the UART Control registers as defined in the Universal Asynchronous Receiver/Transmitter section on page 99.

! Caution: To prevent spurious signals during IrDA data transmission, set the IREN bit in the UART Control 1 Register to 1 to enable the Infrared Encoder/Decoder before enabling the GPIO Port alternate function for the corresponding pin.

- If the internal voltage reference must be output to a pin, set the REFEXT bit to 1. The internal voltage reference must be enabled in this case.
- Write the REFSELL bit of the pair {REFSELH, REFSELL} to select the internal voltage reference level or to disable the internal reference. The REFSELH bit is contained in the ADC Control/Status Register 1.
- Set CEN to 1 to start the conversion.

4. CEN remains 1 while the conversion is in progress. A single-shot conversion requires 5129 system clock cycles to complete. If a single-shot conversion is requested from an ADC powered down state, the ADC uses 40 additional clock cycles to power up before beginning the 5129 cycle conversion.
5. When the conversion is complete, the ADC control logic performs the following operations:
   - 13-bit two's-complement result written to {ADCD_H[7:0], ADCD_L[7:3]}
   - Sends an interrupt request to the Interrupt Controller denoting conversion complete
   - CEN resets to 0 to indicate the conversion is complete
6. If the ADC remains idle for 160 consecutive system clock cycles, it is automatically powered down.

Continuous Conversion

When configured for continuous conversion, the ADC continuously performs an analog-to-digital conversion on the selected analog input. Each new data value overwrites the previous value stored in the ADC Data registers. An interrupt is generated after each conversion.

Caution: In CONTINUOUS Mode, ADC updates are limited by the input signal bandwidth of the ADC and the latency of the ADC and its digital filter. Step changes at the input are not immediately detected at the next output from the ADC. The response of the ADC (in all modes) is limited by the input signal bandwidth and the latency.

Observe the following steps for setting up the ADC and initiating continuous conversion:

1. Enable the appropriate analog input by configuring the general-purpose I/O pins for alternate function. This action disables the digital input and output driver.
2. Write the ADC Control/Status Register 1 to configure the ADC.

Note: The offset compensation is performed first, followed by the gain compensation. One bit of resolution is lost because of rounding on both the offset and gain computations. As a result the ADC registers read back 13 bits: 1 sign bit, two calibration bits lost to rounding and 10 data bits.

Also note that in the second term, the multiplication must be performed before the division by 2^{16}. Otherwise, the second term incorrectly evaluates to zero.

Caution: Although the ADC can be used without the gain and offset compensation, it does exhibit nonunity gain. Designing the ADC with sub-unity gain reduces noise across the ADC range but requires the ADC results to be scaled by a factor of 8/7.

ADC Compensation Details

High-efficiency assembly code that performs ADC compensation is available for download on www.zilog.com. This section offers a bit-specific description of the ADC compensation process used by this code.

The following data bit definitions are used:

0–9, a–f = bit indices in hexadecimal
s = sign bit
v = overflow bit
– = unused

Input Data

MSB	LSB		
s b a 9 8 7 6 5	4 3 2 1 0 – – v	(ADC)	ADC Output Word; if v = 1, the data is invalid
	s 6 5 4 3 2 1 0		Offset Correction Byte
s s s s s 7 6 5	4 3 2 1 0 0 0 0	(Offset)	Offset Byte shifted to align with ADC data
s e d c b a 9 8	7 6 5 4 3 2 1 0	(Gain)	Gain Correction Word

Flash Program Memory Address 0001H

Table 89. Flash Options Bits at Program Memory Address 0001H

Bit	7	6	5	4	3	2	1	0
Field	Reserved			XTLDIS	Reserved			
RESET	U	U	U	U	U	U	U	U
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Address	Program Memory 0001H							

Note: U = Unchanged by Reset. R/W = Read/Write.

Bit	Description
[7:5]	**Reserved** These bits are reserved and must be programmed to 111.
[4] XTLDIS	**State of the Crystal Oscillator at Reset** This bit only enables the crystal oscillator. Its selection as a system clock must be performed manually. 0 = Crystal oscillator is enabled during reset, resulting in longer reset timing. 1 = Crystal oscillator is disabled during reset, resulting in shorter reset timing. **Caution:** Programming the XTLDIS bit to zero on 8-pin versions of this device prevents any further communication via the debug pin due to the fact that the XIN and DBG functions are shared on pin 2 of this package. Do not program this bit to zero on 8-pin devices unless further debugging or Flash programming is not required.
[3:0]	**Reserved** These bits are reserved and must be programmed to 1111.

Crystal Oscillator

The products in the Z8 Encore! XP F082A Series contain an on-chip crystal oscillator for use with external crystals with 32kHz to 20MHz frequencies. In addition, the oscillator supports external RC networks with oscillation frequencies up to 4MHz or ceramic resonators with frequencies up to 8MHz. The on-chip crystal oscillator can be used to generate the primary system clock for the internal eZ8 CPU and the majority of the on-chip peripherals. Alternatively, the X_{IN} input pin can also accept a CMOS-level clock input signal (32kHz–20MHz). If an external clock generator is used, the X_{OUT} pin must be left unconnected. The Z8 Encore! XP F082A Series products do not contain an internal clock divider. The frequency of the signal on the X_{IN} input pin determines the frequency of the system clock.

Note: Although the X_{IN} pin can be used as an input for an external clock generator, the CLKIN pin is better suited for such use (see the System Clock Selection section on page 193).

Operating Modes

The Z8 Encore! XP F082A Series products support four oscillator modes:

- Minimum power for use with very low frequency crystals (32kHz–1MHz)
- Medium power for use with medium frequency crystals or ceramic resonators (0.5MHz to 8MHz)
- Maximum power for use with high frequency crystals (8MHz to 20MHz)
- On-chip oscillator configured for use with external RC networks (<4MHz)

The oscillator mode is selected via user-programmable Flash option bits. See **the** Flash Option Bits chapter on page 159 for information.

Crystal Oscillator Operation

The XTLDIS Flash option bit controls whether the crystal oscillator is enabled during reset. The crystal may later be disabled after reset if a new oscillator has been selected as the system clock. If the crystal is manually enabled after reset through the OSCCTL Register, the user code must wait at least 1000 crystal oscillator cycles for the crystal to stabilize. After this, the crystal oscillator may be selected as the system clock.

Internal Precision Oscillator

The internal precision oscillator (IPO) is designed for use without external components. You can either manually trim the oscillator for a nonstandard frequency or use the automatic factory-trimmed version to achieve a 5.53MHz frequency. IPO features include:

- On-chip RC oscillator that does not require external components
- Output frequency of either 5.53MHz or 32.8kHz (contains both a fast and a slow mode)
- Trimmed through Flash option bits with user override
- Elimination of crystals or ceramic resonators in applications where very high timing accuracy is not required

Operation

An 8-bit trimming register, incorporated into the design, compensates for absolute variation of oscillator frequency. Once trimmed the oscillator frequency is stable and does not require subsequent calibration. Trimming is performed during manufacturing and is not necessary for you to repeat unless a frequency other than 5.53MHz (fast mode) or 32.8kHz (slow mode) is required. This trimming is done at +30ºC and a supply voltage of 3.3V, so accuracy of this operating point is optimal.

If not used, the IPO can be disabled by the Oscillator Control Register (see the Oscillator Control Register Definitions section on page 196).

By default, the oscillator frequency is set by the factory trim value stored in the write-protected Flash information page. However, the user code can override these trim values as described in the Trim Bit Address Space section on page 165.

Select one of two frequencies for the oscillator (5.53MHz and 32.8kHz) using the OSCSEL bits in the the Oscillator Control chapter on page 193.

Assembly Language Source Program Example

```
JP START          ; Everything after the semicolon is a comment.
START:            ; A label called 'START'. The first instruction (JP START) in this
                  ; example causes program execution to jump to the point within the
                  ; program where the START label occurs.
LD R4, R7         ; A Load (LD) instruction with two operands. The first operand,
                  ; Working Register R4, is the destination. The second operand,
                  ; Working Register R7, is the source. The contents of R7 is
                  ; written into R4.
LD 234H, #%01     ; Another Load (LD) instruction with two operands.
                  ; The first operand, Extended Mode Register Address 234H,
                  ; identifies the destination. The second operand, Immediate Data
                  ; value 01H, is the source. The value 01H is written into the
                  ; Register at address 234H.
```

Assembly Language Syntax

For proper instruction execution, eZ8 CPU assembly language syntax requires that the operands be written as 'destination, source'. After assembly, the object code usually has the operands in the order 'source, destination', but ordering is opcode-dependent. The following instruction examples illustrate the format of some basic assembly instructions and the resulting object code produced by the assembler. This binary format must be followed if manual program coding is preferred or if you intend to implement your own assembler.

Example 1. If the contents of registers 43H and 08H are added and the result is stored in 43H, the assembly syntax and resulting object code is:

Table 116. Assembly Language Syntax Example 1

Assembly Language Code	ADD	43H,	08H	(ADD dst, src)
Object Code	04	08	43	(OPC src, dst)

Example 2. In general, when an instruction format requires an 8-bit register address, that address can specify any register location in the range 0–255 or, using Escaped Mode Addressing, a Working Register R0–R15. If the contents of Register 43H and Working Register R8 are added and the result is stored in 43H, the assembly syntax and resulting object code is:

Table 117. Assembly Language Syntax Example 2

Assembly Language Code	ADD	43H,	R8	(ADD dst, src)
Object Code	04	E8	43	(OPC src, dst)

Table 139. Analog-to-Digital Converter Electrical Characteristics and Timing

		V_{DD} = 3.0 V to 3.6 V T_A = 0°C to +70°C (unless otherwise stated)				
Symbol	**Parameter**	**Minimum**	**Typical**	**Maximum**	**Units**	**Conditions**
	Resolution	10		–	bits	
	Differential Nonlinearity (DNL)	–1.0	–	1.0	LSB[3]	External V_{REF} = 2.0 V; $R_S \leftarrow$ 3.0 kΩ
	Integral Nonlinearity (INL)	–3.0	–	3.0	LSB[3]	External V_{REF} = 2.0 V; $R_S \leftarrow$ 3.0 kΩ
	Offset Error with Calibration		±1		LSB[3]	
	Absolute Accuracy with Calibration		±3		LSB[3]	
V_{REF}	Internal Reference Voltage	1.0 2.0	1.1 2.2	1.2 2.4	V	REFSEL=01 REFSEL=10
V_{REF}	Internal Reference Variation with Temperature		±1.0		%	Temperature variation with V_{DD} = 3.0
V_{REF}	Internal Reference Voltage Variation with V_{DD}		±0.5		%	Supply voltage variation with T_A = 30°C
R_{REFOUT}	Reference Buffer Output Impedance		850		W	When the internal reference is buffered and driven out to the VREF pin (REFOUT = 1)
	Single-Shot Conversion Time	–	5129	–	System clock cycles	All measurements but temperature sensor
			10258			Temperature sensor measurement

Notes:
1. Analog source impedance affects the ADC offset voltage (because of pin leakage) and input settling time.
2. Devices are factory calibrated at V_{DD} = 3.3V and T_A = +30°C, so the ADC is maximally accurate under these conditions.
3. LSBs are defined assuming 10-bit resolution.
4. This is the maximum recommended resistance seen by the ADC input pin.
5. The input impedance is inversely proportional to the system clock frequency.

Table 142. Temperature Sensor Electrical Characteristics

		V_{DD} = 2.7 V to 3.6 V				
Symbol	**Parameter**	**Minimum**	**Typical**	**Maximum**	**Units**	**Conditions**
T_{AERR}	Temperature Error		±0.5	±2	°C	Over the range +20°C to +30°C (as measured by ADC).[1]
			±1	±5	°C	Over the range +0°C to +70°C (as measured by ADC).
			±2	±7	°C	Over the range +0°C to +105°C (as measured by ADC).
			±7		°C	Over the range –40°C to +105°C (as measured by ADC).
t_{WAKE}	Wakeup Time		80	100	µs	Time required for Temperature Sensor to stabilize after enabling.

Note: Devices are factory calibrated at for maximal accuracy between +20°C and +30°C, so the sensor is maximally accurate in that range. User recalibration for a different temperature range is possible and increases accuracy near the new calibration point.

General Purpose I/O Port Output Timing

Figure 35 and Table 144 provide timing information for GPIO port pins.

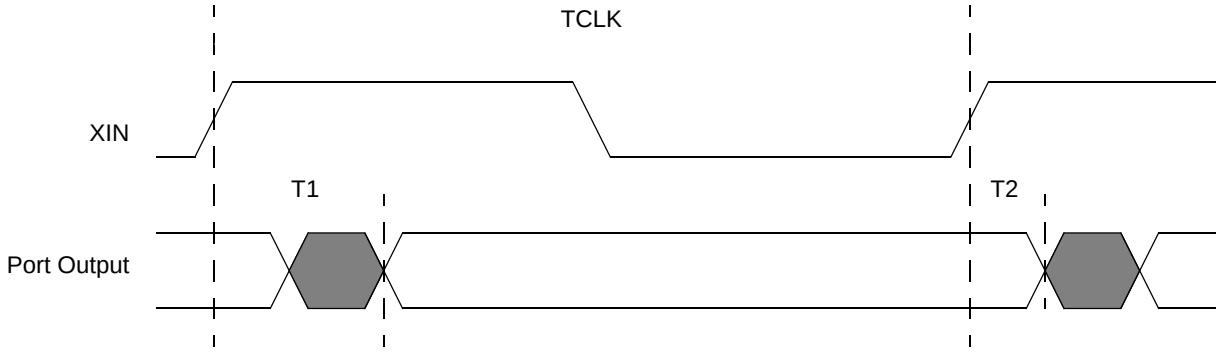

Figure 35. GPIO Port Output Timing

Table 144. GPIO Port Output Timing

		Delay (ns)	
Parameter	**Abbreviation**	**Minimum**	**Maximum**
GPIO port pins			
T_1	X_{IN} Rise to Port Output Valid Delay	–	15
T_2	X_{IN} Rise to Port Output Hold Time	2	–

P

R

Z